

Title (en)

METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE AND SUPPORT PLATE THEREFOR

Title (de)

HERSTELLUNGSVERFAHREN FÜR HALBLEITERVORRICHTUNG UND TRÄGER DAFÜR

Title (fr)

PROCEDE DE PRODUCTION D'UN DISPOSITIF A SEMI-CONDUCTEUR, DISPOSITIF A SEMI-CONDUCTEUR AINSI OBTENU ET PLAQUE DE SUPPORT ADAPTEE POUR CE DISPOSITIF A SEMI-CONDUCTEUR

Publication

**EP 1386345 A2 20040204 (EN)**

Application

**EP 02720409 A 20020422**

Priority

- EP 02720409 A 20020422
- EP 01201524 A 20010426
- IB 0201446 W 20020422

Abstract (en)

[origin: WO02089184A2] The invention relates to a method of manufacturing a semiconductor device (10) comprising a semiconductor element (1), with two or more elements (1) being attached to a support plate (2). It is often desired in such a case that the elements(1) are positioned on the support plate (2) or on a further support plate (22) at a larger mutual distance than in the semiconductor body (100) in which the elements (1) are formed. According to the invention, the support plate (2) is formed as an array of rigid subplates (2A) to which the elements (1) are attached, and the rigid subplates (2A) are interconnected within the plate (2) by means of one or more flexible elements (3). In this way the elements (1) - after they have been attached to the support plate (2) and after they have been separated from each other within the semiconductor body (100) and after stretching of the flexible elements (3) - can be positioned in an accurate manner at a larger mutual distance. Subsequently - or after having been transferred to a further plate (22) - the elements (1) may be provided with an encapsulation (20) and can be mounted on to individual semiconductor devices (10).

IPC 1-7

**H01L 21/00**

IPC 8 full level

**H01L 23/12** (2006.01); **H01L 21/00** (2006.01); **H01L 21/56** (2006.01); **H01L 21/673** (2006.01); **H01L 21/68** (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP)

**H01L 21/6835** (2013.01); **H01L 24/33** (2013.01)

Citation (search report)

See references of WO 02089184A2

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

**WO 02089184 A2 20021107**; **WO 02089184 A3 20030109**; EP 1386345 A2 20040204; JP 2004520717 A 20040708

DOCDB simple family (application)

**IB 0201446 W 20020422**; EP 02720409 A 20020422; JP 2002586386 A 20020422